L Number	Hits	Search Text	DB	Time stamp
1	1168	((438/690) or (438/750) or (438/734) or (438/737)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 13:20
-	16	US-5164815-$.DID. OR US-5313102-$.DID. OR US-5476566-$.DID. OR US-5583372-$.DID. OR US-0618406-$.DID. OR US-0624567-$.DID. OR US-0625819-$.DID. OR US-0627997-$.DID. OR US-6403449-$.DID. OR US-0650668-$.DID. OR US-0653441-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:20
-	23	US-5164815-$.DID. OR US-5313102-$.DID. OR US-5476566-$.DID. OR US-5583372-$.DID. OR US-6184064-$.DID. OR US-6245677-$.DID. OR US-6258198-$.DID. OR US-6279976-$.DID. OR US-6403449-$.DID. OR US-6506681-$.DID. OR US-6534419-$.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:21
-	60162	backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:40
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 18:59
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:46
-	1929343	coat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:44
-	293421	cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:42
-	0	backside near4 (chip or die or dice or ic or integrated adj circuit) near8 coat$4 near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near6 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:46
-	0	backside near4 (chip or die or dice or ic or integrated adj circuit) same coat$4 same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:47
-	13	backside near4 (chip or die or dice or ic or integrated adj circuit) and backside same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:24
-	8	backside near4 (chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:20

-	8	(backside near4 (chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)) not (backside near4 (chip or die or dice or ic or integrated adj circuit) and backside same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:17
-	23	(chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:33
-	15	((chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)) not (backside near4 (chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:20
-	6	(chip or die or dice or ic or integrated adj circuit) and backside near8 passivat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:30
-	198	(chip or die or dice or ic or integrated adj circuit) and backside same coat$4 same ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:34
-	175	((chip or die or dice or ic or integrated adj circuit) and backside same coat$4 same ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 coat$4 near8 ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:08
-	6	((chip or die or dice or ic or integrated adj circuit) and backside same coat$4 same ((cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) or backgrind$)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:34
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:09
-	1300622	peaks or valleys or hill or hillocks or rough$4 or jagged or uneven	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:54
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:20
-	293421	cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:12
-	4042332	smooth$6 or even$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:12

-		1	(chip or die or dice or ic or integrated adj circuit) and (peaks or valleys or hill or hillocks or rough$4 or jagged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near6 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near6 (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:14
-		161	(chip or die or dice or ic or integrated adj circuit) and (peaks or valleys or hill or hillocks or rough$4 or jagged or uneven) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) same (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:13
-		14	(chip or die or dice or ic or integrated adj circuit) and (peaks or valleys or hill or hillocks or rough$4 or jagged or uneven) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near6 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:19
-		1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:20
-		0	(chip or die or dice or ic or integrated adj circuit) and sacrificial$4 near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near4 (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:43
-		0	(chip or die or dice or ic or integrated adj circuit) and sacrificial$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) same backside	USPAT; US-PGPUB; ·EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:21
-		31	(chip or die or dice or ic or integrated adj circuit) and sacrificial$4 near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:22
-		18	(chip or die or dice or ic or integrated adj circuit) and sacrificial$4 near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near4 (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:46
-		18	(chip or die or dice or ic or integrated adj circuit) and sacrificial$4 near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near4 (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:52
-		2	20040065554.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:47
-		1632127	(chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:52
-		1632127	(chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:52
-		18	((chip or die or dice or ic or integrated adj circuit)) and sacrificial$4 near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near4 (smooth$6 or even$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:53

-	1133	((chip or die or dice or ic or integrated adj circuit)) and sacrificial$4 near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:54
-	1300622	peaks or valleys or hill or hillocks or rough$4 or jagged or uneven	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:42
-	12	((chip or die or dice or ic or integrated adj circuit)) and (peaks or valleys or hill or hillocks or rough$4 or jagged or uneven) near8 sacrificial$4 near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 22:54
-	1300622	peaks or valleys or hill or hillocks or rough$4 or jagged or uneven	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:42
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:43
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:43
-	293421	cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:43
-	120	(chip or die or dice or ic or integrated adj circuit) and (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near8 expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 11:45
-	6	(chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near8 expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:18
-	217	(chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) and (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near4 expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:11
-	13	(chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near16 expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:17
-	6	(chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near8 expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:18
-	7	((chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near16 expos$4) not ((chip or die or dice or ic or integrated adj circuit) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) near8 (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) near8 expos$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:18

-	8	backside near4 (chip or die or dice or ic or integrated adj circuit) and backside same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene) same (cmp or chemical adj mechanical or polish$4 or planariz$4 or planaris$4) same expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 13:24
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:47
-	2185088	polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:38
-	1414770	sio? or "sio.sub.2" or oxide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:49
-	60162	backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:54
-	1567914	sio? or "sio.sub.2" or oxide or oxidiz$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:50
-	2	(chip or die or dice or ic or integrated adj circuit) and backside near4 (sio? or "sio.sub.2" or oxide or oxidiz$4) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:51
-	1983	expos$4 near4 backside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:51
-	0	((chip or die or dice or ic or integrated adj circuit) and backside near4 (sio? or "sio.sub.2" or oxide or oxidiz$4) near4 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) and (expos$4 near4 backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:55
-	25	(chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:38
-	1	((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) and (expos$4 near4 backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:52
-	161	(chip or die or dice or ic or integrated adj circuit) and backside same (sio? or "sio.sub.2" or oxide or oxidiz$4) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 14:54
-	179323	backside or bottom adj side or flip adj side or flipside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:40

-	20	((chip or die or dice or ic or integrated adj circuit) and backside same (sio? or "sio.sub.2" or oxide or oxidiz$4) same (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) and (expos$4 near4 backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 15:07
-	0	("2003/0096507" | "2003/0219912").PN.	USPAT	2004/09/20 15:07
-	0	("2003/0096507" | "2003/0219912").PN.	USPAT	2004/09/20 15:07
-	0	6777334.URPN.	USPAT	2004/09/20 15:07
-	2	(("20030096507") or ("20030219912")).PN.	USPAT; US-PGPUB	2004/09/20 16:11
-	1525	releas$4 near4 "27" and (chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:12
-	269	releas$4 near4 (backside or bottom adj side or flip adj side or flipside) and (chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:13
-	309631	backside or bottom adj side or (flip or back) adj side or flipside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:13
-	571771	backside or bottom adj side or (flip or back or under) adj side or flipside or underside	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:13
-	142	releas$4 near4 (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) same (chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:14
-	32	(chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:49
-	7	((chip or die or dice or ic or integrated adj circuit) and (backside or bottom adj side or (flip or back or under) adj side or flipside or underside) near8 (sio? or "sio.sub.2" or oxide or oxidiz$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene)) not ((chip or die or dice or ic or integrated adj circuit) and backside near8 (sio? or "sio.sub.2" or oxide or oxidiz$4) near8 (polymer or epoxy or epoxies or silicone or urethane or siloxane or parylene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 16:49
-	399333	epoxy or epoxies	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 18:59
-	48	(chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:41
-	0	((chip or die or dice or ic or integrated adj circuit) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)) and ((expos$4 or remov$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:42
-	4	(expos$4 or remov$4) near4 (backside or bottom adj side or flip adj side or flipside) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 17:42

-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:16
-	399333	epoxy or epoxies	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:00
-	156266	thermoset$6 or thermo adj set$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:00
-	2026815	substrate or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:08
-	4671698	remov$4 or etch$4 or expos$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:18
-	3823	(chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or expos$4) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:05
-	93	(chip or die or dice or ic or integrated adj circuit) and (epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or expos$4) near4 (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:09
-	1632127	chip or die or dice or ic or integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:08
-	2026815	substrate or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:08
-	169	(epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or expos$4) near4 (epoxy or epoxies) near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:13
-	55	(epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or expos$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:19
-	4003371	remov$4 or etch$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:18
-	4120690	remov$4 or etch$4 or cmp or polish$4 or planariz$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:18

-	14	(epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:36
-	64	(remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((substrate or wafer) or surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:40
-	12	((remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((substrate or wafer) or surface)) and (thermoset$6 or thermo adj set$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:38
-	1	(((remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((substrate or wafer) or surface)) and (thermoset$6 or thermo adj set$6)) not ((epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 19:38
-	53	((remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((substrate or wafer) or surface)) not ((epoxy or epoxies) near8 (thermoset$6 or thermo adj set$6) and (remov$4 or etch$4 or cmp or polish$4 or planariz$4) near4 (epoxy or epoxies) near4 expos$4 near4 ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer) or surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:24
-	20672	(thermoset$6 or thermo adj set$6) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:24
-	215	(epoxy or epoxies) near4 (screen or stencil or spin) near coat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:25
-	0	partial$4 near2 (cur$4 or set$6 or harden$4) near4 (epoxy or epoxies) near4 (before or subsequent$4) near4 apply$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:28
-	865	partial$4 near2 (cur$4 or set$6 or harden$4) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:29
-	3	((thermoset$6 or thermo adj set$6) near4 (epoxy or epoxies)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat$4) and (partial$4 near2 (cur$4 or set$6 or harden$4) near4 (epoxy or epoxies)) and ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:37
-	42	partial$4 near2 (cur$4 or set$6 or harden$4) near4 (epoxy or epoxies) near4 (before or subsequent$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:32
-	2	tacky near4 (epoxy or epoxies) near4 (before or subsequent$4) near4 (coat$4 or apply$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:39

-	144	(epoxy or epoxies) near4 (cur$4 or harden$4 or set$6) near4 (before or subsequent$4) near4 (coat$4 or apply$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:34
-	0	((epoxy or epoxies) near4 (cur$4 or harden$4 or set$6) near4 (before or subsequent$4) near4 (coat$4 or apply$4)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat$4) and ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:39
-	14	(epoxy or epoxies) near4 (hardener) near4 (before or subsequent$4) near4 (coat$4 or apply$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:40
-	0	((epoxy or epoxies) near4 (hardener) near4 (before or subsequent$4) near4 (coat$4 or apply$4)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat$4) and ((chip or die or dice or ic or integrated adj circuit) or (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:40
-	10282	(epoxy or epoxies) near4 (hardener)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:40
-	5	((epoxy or epoxies) near4 (hardener)) and ((epoxy or epoxies) near4 (screen or stencil or spin) near coat$4) and ((epoxy or epoxies) or thermal$4 or heat$4) near4 (epoxy or epoxies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 20:59
-	223	tape same releas$4 near2 (film or layer) same backing and (chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:01
-	21	tape near8 releas$4 near2 (film or layer) near8 backing same (chip or die or dice or ic or integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:09
-	256	tape near8 releas$4 near2 (film or layer) near8 backing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:09
-	152599	(chip or die or dice or ic or integrated adj circuit) near4 (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:12
-	3	(tape near8 releas$4 near2 (film or layer) near8 backing) and ((chip or die or dice or ic or integrated adj circuit) near4 (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:14
-	168580	((chip or die or dice or ic or integrated adj circuit) or packag$4) near4 (substrate or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:14
-	11	(tape near8 releas$4 near2 (film or layer) near8 backing) and (((chip or die or dice or ic or integrated adj circuit) or packag$4) near4 (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:15

-	101	(chip or die or dice or ic or integrated adj circuit) near4 (backing near4 tap$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:17
-	4	(tape same releas$4 near2 (film or layer) same backing and (chip or die or dice or ic or integrated adj circuit)) and ((chip or die or dice or ic or integrated adj circuit) near4 (backing near4 tap$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/20 21:17